



X-30-4377U

Shin-Etsu Silicones of America, Inc.
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Product Description

X-30-4377U is a 60 durometer high strength and one of a series of easy processing silicone rubber bases. It is used in a variety of applications. X-30-4377U can be molded, extruded, or calendared.

Product Features

- This product can be blended with other Shin-Etsu general purpose or no post cure bases for intermediate properties. The choice between these bases will depend on specific requirements.

Typical Properties

Type of HCR	High Strength
Cure Agent	C-25 A/B
Durometer	60
Tensile Strength (psi)	1520
Elongation (%)	600
Specific Gravity	1.16
Tear Die B (ppi)	55
Cure Time (minutes)	10
Cure Temp. (°C)	120
Cure Temp. (°F)	248
Post Cure Time (hours)	4
Post Cure Temp. (°C)	200
Post Cure Temp. (°F)	392

Note: Values are not for specification purposes.

Storage and Shelf Life

Store in a cool, dry place.

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